MC10EP32

÷2 Divider

The MC10EP32 is an integrated ÷2 divider. The differential clock inputs and the V_{BB} allow a differential, single–ended or AC coupled interface to the device. If used, the V_{BB} output should be bypassed to ground with a 0.01μF capacitor.

The reset pin is asynchronous and is asserted on the rising edge. Upon power–up, the internal flip–flops will attain a random state; the reset allows for the synchronization of multiple EP32's in a system.

- 250ps Typical Propagation Delay
- 3 GHz Typical Toggle Frequency
- PECL mode: 3.0V to 5.5V V_{CC} with V_{EE} = 0V
- ECL mode: 0V V_{CC} with V_{EE} = –3.0V to –5.5V
- Internal Input Resistors: Pulldown on D, $\overline{D}$
- Q Output will default LOW with inputs open or at V_{EE}
- ESD Protection: >4KV HBM, >200V MM
- V_{BB} Output
- New Differential Input Common Mode Range
- Moisture Sensitivity Level 1, Indefinite Time Out of Drypack
- Flammability Rating: UL–94 code V–0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 78 devices

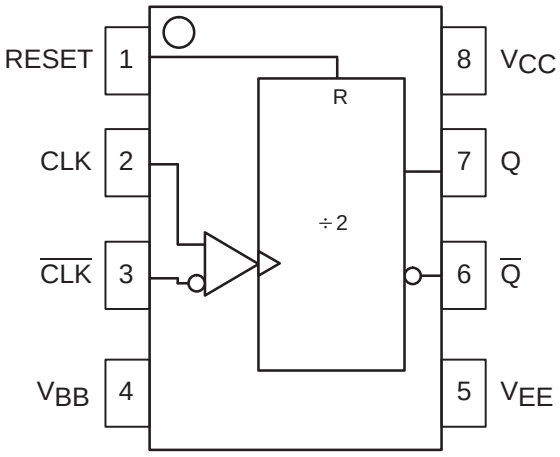

Figure 1. 8–Lead Pinout (Top View) **and Logic Diagram**

ON Semiconductor
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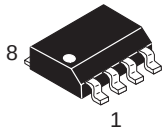
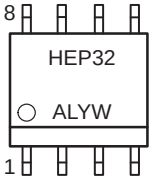


SO–8
D SUFFIX
CASE 751

MARKING DIAGRAM



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*For additional information, see Application Note AND8002/D

PIN DESCRIPTION	
PIN	**FUNCTION**
CLK, $\overline{CLK}$	ECL Clock Inputs
Reset	ECL Asynchronous Reset
V_{BB}	Reference Voltage Output
Q, $\overline{Q}$	ECL Data Outputs
V_{CC}	Positive Supply
V_{EE}	Negative, 0 Supply

TRUTH TABLE				
CLK	**$\overline{CLK}$**	**RESET**	**Q**	**$\overline{Q}$**
X Z	X $\overline{Z}$	Z L	L F	H F

Z = LOW to HIGH Transition
$\overline{Z}$ = HIGH to LOW Transition
F = Divide by 2 Function

ORDERING INFORMATION

Device	Package	Shipping
MC10EP32D	SOIC	98 Units/Rail
MC10EP32DR2	SOIC	2500 Tape & Reel

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{EE}	Power Supply (V_{CC} = 0V)	–6.0 to 0	VDC
V_{CC}	Power Supply (V_{EE} = 0V)	6.0 to 0	VDC
V_I	Input Voltage (V_{CC} = 0V, V_I not more negative than V_{EE})	–6.0 to 0	VDC
V_I	Input Voltage (V_{EE} = 0V, V_I not more positive than V_{CC})	6.0 to 0	VDC
I_{out}	Output Current Continuous Surge	50 100	mA
I_{BB}	V_{BB} Sink/Source Current†	± 0.5	mA
T_A	Operating Temperature Range	–40 to +85	°C
T_{stg}	Storage Temperature	–65 to +150	°C
θ_{JA}	Thermal Resistance (Junction–to–Ambient) Still Air 500lfpm	190 130	°C/W
θ_{JC}	Thermal Resistance (Junction–to–Case)	41 to 44 ± 5%	°C/W
T_{sol}	Solder Temperature (<2 to 3 Seconds: 245°C desired)	265	°C

* Maximum Ratings are those values beyond which damage to the device may occur.

† Use for inputs of same package only.

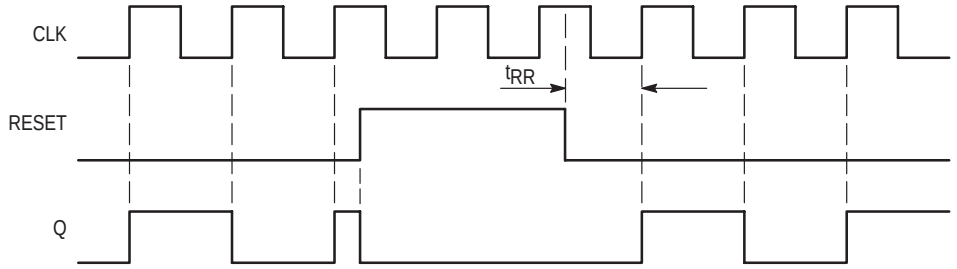


Figure 2. Timing Diagram

DC CHARACTERISTICS, ECL/LVECL (V_{CC} = 0V; V_{EE} = –5.5V to –3.0V) (Note 4.)

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
IEE	Power Supply Current (Note 1.)	23	30	37	23	30	37	23	30	37	mA
V_{OH}	Output HIGH Voltage (Note 2.)	–1135	–1060	–885	–1070	–945	–820	–1010	–885	–760	mV
V_{OL}	Output LOW Voltage (Note 2.)	–1935	–1810	–1685	–1870	–1745	–1620	–1810	–1685	–1560	mV
V_{IH}	Input HIGH Voltage Single Ended	–1210		–885	–1145		–820	–1085		–760	mV
V_{IL}	Input LOW Voltage Single Ended	–1935		–1610	–1870		–1545	–1810		–1485	mV
V_{BB}	Output Voltage Reference	–1510	–1410	–1310	–1445	–1345	–1245	–1385	–1285	–1185	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Note 3.)	V_{EE}+2.0		0.0	V_{EE}+2.0		0.0	V_{EE}+2.0		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current CLK $\overline{CLK}$	0.5 –150			0.5 –150			0.5 –150			μA

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

1. V_{CC} = 0V, V_{EE} = V_{EEmin} to V_{EEmax}, all other pins floating.
2. All loading with 50 ohms to V_{CC}–2.0 volts.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.
4. Input and output parameters vary 1:1 with V_{CC}.

DC CHARACTERISTICS, LVPECL (V_{CC} = 3.3V ± 0.3V, V_{EE} = 0V) (Note 8.)

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
IEE	Power Supply Current (Note 5.)	23	30	37	23	30	37	23	30	37	mA
V_{OH}	Output HIGH Voltage (Note 6.)	2165	2240	2415	2230	2355	2480	2290	2415	2540	mV
V_{OL}	Output LOW Voltage (Note 6.)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V_{IH}	Input HIGH Voltage Single Ended	2090		2415	2155		2480	2215		2540	mV
V_{IL}	Input LOW Voltage Single Ended	1365		1690	1430		1755	1490		1815	mV
V_{BB}	Output Voltage Reference	1790	1890	1990	1855	1955	2055	1915	2015	2115	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Note 7.)	2.0		3.3	2.0		3.3	2.0		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current CLK $\overline{CLK}$	0.5 –150			0.5 –150			0.5 –150			μA

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

5. V_{CC} = 3.3V, V_{EE} = 0V, all other pins floating.
6. All loading with 50 ohms to V_{CC}–2.0 volts.
7. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.
8. Input and output parameters vary 1:1 with V_{CC}.

DC CHARACTERISTICS, PECL (V_{CC} = 5.0V ± 0.5V, V_{EE} = 0V) (Note 12.)

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
IEE	Power Supply Current (Note 9.)	23	30	37	23	30	37	23	30	37	mA
V_{OH}	Output HIGH Voltage (Note 10.)	3865	3940	4115	3930	4055	4180	3990	4115	4240	mV
V_{OL}	Output LOW Voltage (Note 10.)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
V_{IH}	Input HIGH Voltage Single Ended	3790		4115	3855		4180	3915		4240	mV
V_{IL}	Input LOW Voltage Single Ended	3065		3390	3130		3455	3190		3515	mV
V_{BB}	Output Voltage Reference	3490	3590	3690	3555	3655	3755	3615	3715	3815	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Note 11.)	2.0		5.0	2.0		5.0	2.0		5.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current CLK $\overline{CLK}$	0.5 –150			0.5 –150			0.5 –150			μA

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

9. V_{CC} = 5.0V, V_{EE} = 0V, all other pins floating.
10. All loading with 50 ohms to V_{CC}–2.0 volts.
11. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.
12. Input and output parameters vary 1:1 with V_{CC}.

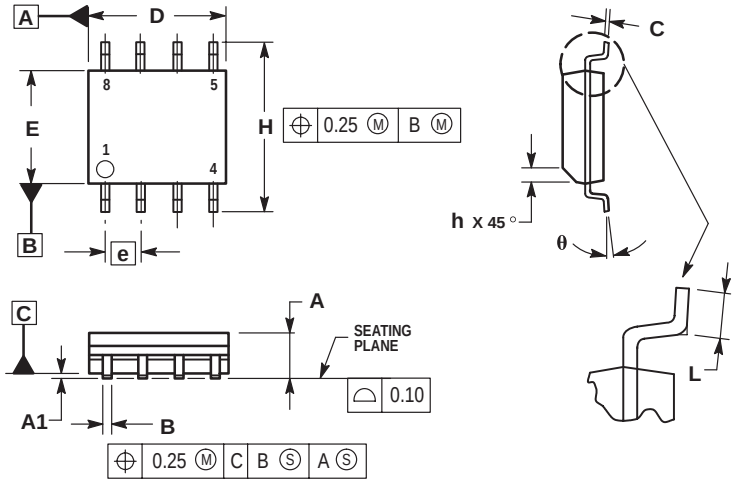
AC CHARACTERISTICS (V_{CC} = 0V; V_{EE} = –3.0V to –5.5V) or (V_{CC} = 3.0V to 5.5V; V_{EE} = 0V)

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency (Note 13.)	2.5	3.0		2.5	3.0		2.5	3.0		GHz
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential CLK–>Q, $\overline{Q}$ RESET–>Q, $\overline{Q}$	100 100	220 220	300 300	100 100	250 250	350 350	180 180	290 290	400 400	ps
t_{RR}	Set/Reset Recovery	200	175		200	175		200	175		ps
t_{SKEW}	Duty Cycle Skew (Note 14.)		5.0			5.0	20		5.0	20	ps
t_{PW}	Minimum Pulse Width RESET	550	475		550	475		550	475		ps
t_{JITTER}	Cycle–to–Cycle Jitter		TBD			TBD			TBD		ps
V_{PP}	Input Voltage Swing (Diff.)	150	800	1200	150	800	1200	150	800	1200	mV
t_r t_f	Output Rise/Fall Times Q, $\overline{Q}$ (20% – 80%)	50	100	150	70	120	170	70	130	200	ps

13. F_{max} guaranteed for functionality only. V_{OL} and V_{OH} levels are guaranteed at DC only.
14. Skew is measured between outputs under identical transitions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.

PACKAGE DIMENSIONS

SO–8
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751–06
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS ARE IN MILLIMETER.
3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
θ	0°	7°

Notes

Notes

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